Bare Die and Wafer
Part Numbering & Packing Guide

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This specification defines the method for bare die packing and part number identification. Example: Bipolar Power NPN Darlington Transistor Die, 2N6300, with optional up-screening to MIL-PRF-38534 Class H equivalent, Tray (Waffle) Package.

**Bare Die Part Numbering System**

- **CENTRAL PROCESS NUMBER**
  - (5 - 7 ALPHA/NUMERIC)
  - CPxxx = Transistor
  - CPZxx = Zener Diode
  - CPDxx = Diode
  - CPQxx = TRIAC
  - CPSxx = SCR
  - CPCxx = Silicon Carbide

- **DEVICE TYPE NUMBER**
  - (10 ALPHA/NUMERIC MAX)
  - PREFIX FOR OPTIONAL UP-SCREENING*
    - H = MIL-PRF-38534 Class H equivalent
    - K = MIL-PRF-38534 Class K equivalent
    - HC = MIL-PRF-19500 JANHC equivalent
    - KC = MIL-PRF-19500 JANKC equivalent
    - CEN = Customer-specific up-screening
  - *Non up-screened devices will not include this prefix.

- **PACKING METHOD**
  - CM = Singulated bare die, 100% electrically tested, 100% visually inspected, reject die removed, tray (waffle) package
  - CT = Singulated bare die, 100% electrically tested, reject die removed, tray (waffle) package
  - WN = Wafer form, 100% electrically tested, reject die inked
  - WR = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and plastic ring, reject die inked
  - WS* = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and metal frame, reject die inked
  - *WS is by special order only.

Visit the Central website for a complete listing of all available WR and WS specifications:

www.centralsemi.com/bare-die
BARE DIE PACKING OPTIONS

BARE DIE IN TRAY (WAFFLE) PACK
CT: Singulated die in tray (waffle) pack.
   (example: CP211-PART NUMBER-CT)
CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
   (example: CP211-PART NUMBER-CM)

UNSAWN WAFER
WN: Full wafer, unsawn, 100% tested with reject die inked.
   (example: CP211-PART NUMBER-WN)

SAWN WAFER ON PLASTIC RING
WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.
   (example: CP211-PART NUMBER-WR)
Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.

Visit the Central website for a complete listing of specifications:
www.centralsemi.com/bdspecs

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